

Bluetooth LE Module **ME54BS03**



Datasheet

V 1.0.0



Version Note

Version	Details	Contributor(s)	Date	Notes
1.0.0	First edit	Owen	2024.10.18	

Part Number

Model	Hardware Code
ME54BS03	3Y15TI

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https://en.minewsemi.com/file/ME54BS03-nRF54L15_Datasheet_K_EN.pdf



ME54BS03-nRF54L15

Cost-effective, Ultra-low Power Bluetooth Module with BLE 6.0

ME54BS03 is a highly flexible, ultra-low power, cost-effective Bluetooth module based on nRF54L15. Its powerful Arm® Cortex®-M33 CPU, the core running speed of 128Mhz, in addition, it also comes with 1.5MB NVM space, 256 KB RAM. The hardware is equipped with U.FL, and the integrated design highlights the higher performance of the nRF54 series. At the same time, the ultra-low system power consumption and excellent RF performance as well as other powerful supporting resources can provide a perfect solution for Bluetooth connection.

FEATURES



Bluetooth 6.0



High cost
performance



Ultra-low
Power



Hardware support for Bluetooth
mesh, Thread, Matter and other
protocol development

KEY PARAMETER

ME54BS03

Chip Model	nRF54L15	Antenna	U.FL
Module Size	23.2×17.4×2mm	GPIO	19
Flash	1.5MB	RAM	256KB
Receiving Sensitivity	-96dBm	Transmission Power	-40~+7dBm
Current(TX)	0dBm-5mA	Current(RX)	3.2mA

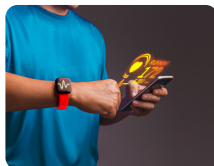
APPLICATION



Smart
Home



Computer
Accessories



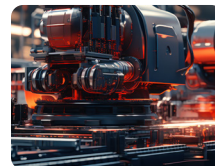
Virtual reality and
Augmented reality



Game controllers
and Remotes



Medical Devices



Industrial IoT

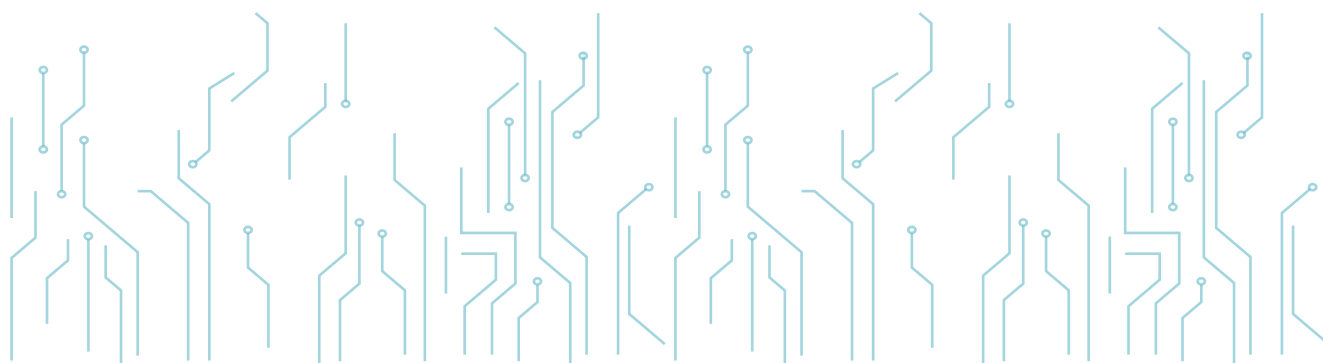
CERTIFICATION





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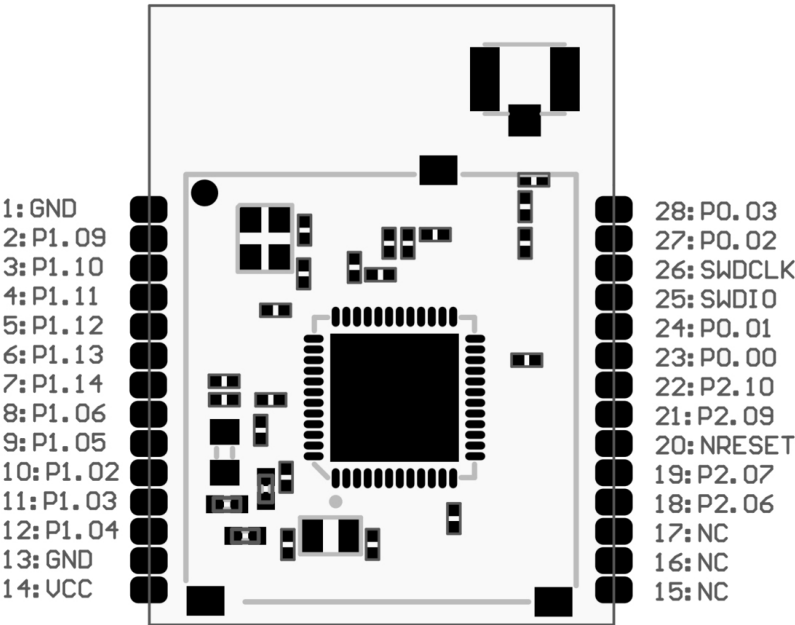
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ELECTRICAL SPECIFICATION

Parameter	Values	Notes
Working Voltage	1.7V-3.6V	To ensure RF work, supply voltage suggest not lower than 2.3V
Working Temperature	-40℃~+105℃	Operating temperature from -40℃ to 105℃
Transmission Power	-40~+7dBm	Configurable
Current(RX)	3.2mA	RF receiving current under 1Mbps pattern
Current(TX)	5mA	RF transmission current under 0dBm pattern
Module Dimension	23.2x17.4x2mm	
Quantity of IO Port	19	

2

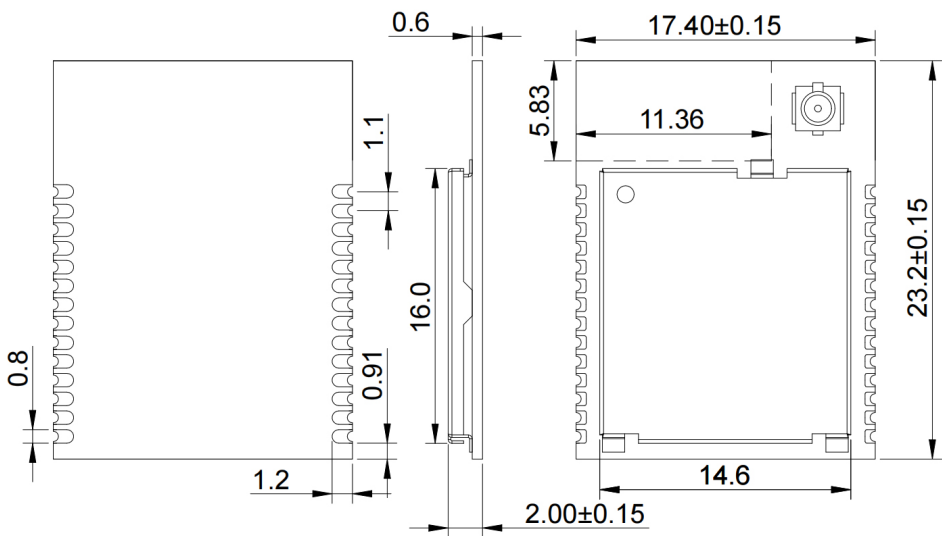
PIN DESCRIPTION



3 PIN DEFINITION

Pin Number	Symbol	Type	Definition
1/13	GND	GND	GND
2-12	P1.02-P1.06/ P1.09-P1.14	I/O	General IO Port
14	VCC	VCC	Power supply, default 1.8V-3.6V
15-17	NC	NC	Empty pins
18-19	P2.06/P2.07	I/O	General IO Port
20	NRESET	Reset pin	Reset
21-24	P2.03-P2.10/ P0.00-P0.01	I/O	General IO Port
25/26	SWDIO/SWDCLK	Burn Pins	Programming pin, when programming, just connect the power supply pin, ground, and these two pins
27-28	P0.02-P0.03	I/O	General IO Port

4 MECHANICAL DRAWING





Default unit: mm Default tolerance: ±0.15

5 PCB LAYOUT

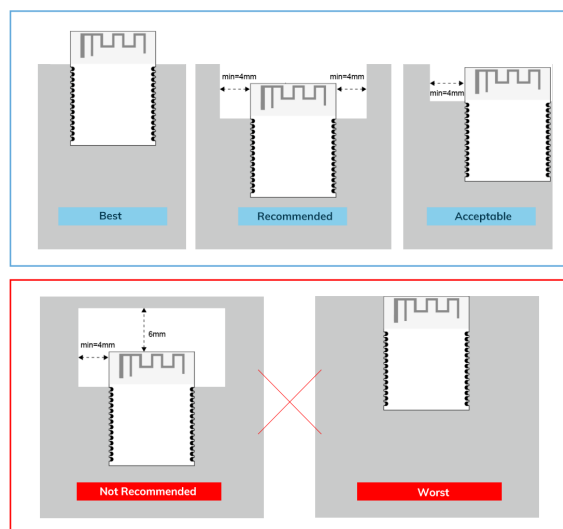
There should be no GND plane or metal cross wiring in the module antenna area, and no components should be placed nearby. It is best to make a hollow or clear area, or place it on the edge of the PCB board. The reference example is as follows:



Notice: It is strongly recommended to use the first design method. The module antenna design is debugged according to the first wiring.

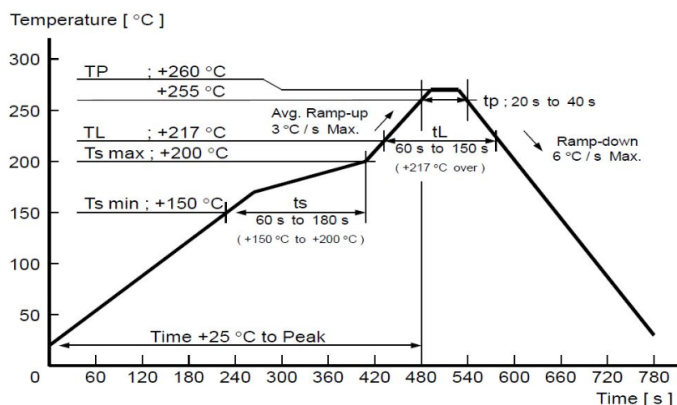
Layout Notes:

- 1) The module's antenna area should be completely clear of any metal obstructions to avoid affecting antenna performance (as shown in the diagram).
- 2) Outside the module's antenna area, try to maintain a solid copper pour to minimize interference from the mainboard signal lines or other sources.
- 3) A clear area of at least 4mm should surround the module's antenna (including its casing) to reduce interference with the antenna.
- 4) Ensure good grounding for components to minimize parasitic inductance.
- 5) Do not place copper under the module's antenna to prevent interference with signal radiation, which could affect transmission distance.
- 6) The antenna should be kept away from other circuits to maintain radiation efficiency and avoid impacting the normal operation of other circuits.
- 7) Position the module as close to the edge of the circuit board as possible, away from other circuitry.
- 8) It is recommended to use a ferrite bead for isolation when connecting the module to the power supply.



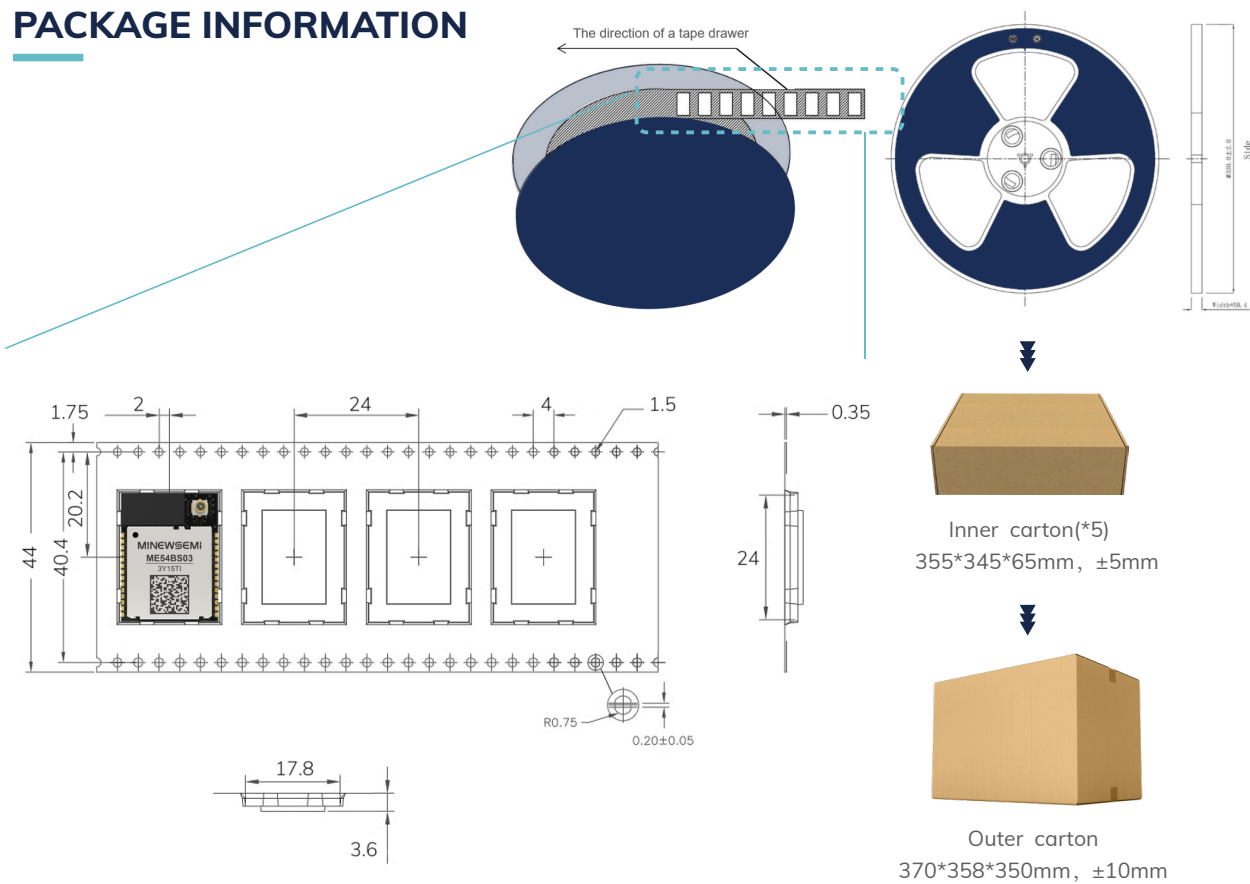
6 REFLOW AND SOLDERING

- 1) Perform SMT according to the reflow oven temperature profile provided below, with a maximum temperature of 260°C;
- 2) Follow IPC/JEDEC standards; Peak temperature: < 260°C; Number of reflows: ≤ 2 times; For SMT involving double-sided placement, it is recommended that the module side undergoes reflow soldering only once. For any special processes, please contact our company.
- 3) Module SMT recommended steel mesh thickness 0.13-0.15mm;
- 4) After opening, if the entire package is not used at once, it should be stored in a vacuum to prevent long-term exposure to air, which can cause moisture absorption and pad oxidation. If there is a gap of 7 to 30 days before reuse, it is recommended to bake the tape at 65-70°C for 24 hours without unrolling it before returning to SMT.
- 5) ESD protection measures should be implemented before using SMT.



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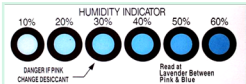
PACKAGE INFORMATION



Remarks
General material list for FCL packaging:



Carrier tape packaging tray



Humidity Indicator
(1 pcs/bag)



Desiccant
(placed in a vacuum bag)



Vacuum bag



Inner carton(*5)
355*345*65mm, ±5mm



Outer carton
370*358*350mm, ±10mm

Other:

Moisture-proof label (attached to the vacuum bag)

Certification label (attached to the vacuum bag)

Outer box label

Default unit: mm Default tolerance: ±0.1

Packing detail	Specification	Net weight	Gross weight	Dimension
ME54BS03	650PCS	734.5g	1565.5g	W=44mm, T=0.35mm

Note: Default weight tolerance all are within 10g (except the special notes)

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions:

- (1) This device may not cause harmful interference
- (2) This device must accept any interference received, including interference that may cause undesired operation.

8 FCC WARNING

Any Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the device.

Note: This device has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This device generates uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this device does cause harmful interference to radio or television reception, which can be determined by turning the device off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the device and receiver.
- Connect the device into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

The device has been evaluated to meet general RF exposure requirement. It can be used in portable exposure condition without restriction.

Requirement per KDB996369 D03

2.2 List of applicable FCC rules

List the FCC rules that are applicable to the modular transmitter. These are the rules that specifically establish the bands of operation, the power, spurious emissions, and operating fundamental frequencies. DO NOT list compliance to unintentional-radiator rules (Part 15 Subpart B) since that is not a condition of a module grant that is extended to a host manufacturer. See also Section 2.10 below concerning the need to notify host manufacturers that further testing is required.³Explanation: This module meets the requirements of FCC part 15C(15.247).

2.3 Summarize the specific operational use conditions

Describe use conditions that are applicable to the modular transmitter, including for example any limits on antennas, etc. For example, if point-to-point antennas are used that require reduction in power or compensation for cable loss, then this information must be in the instructions. If the use condition limitations extend to professional users, then instructions must state that this information also extends to the host manufacturer's instruction manual. In addition, certain information may also be needed, such as peak gain per frequency band and minimum gain, specifically for master devices in 5 GHz DFS bands.

Explanation: The EUT has a PCB Antenna, , and the antenna use a permanently attached Antenna which is not replaceable.

2.4 Limited module procedures

If a modular transmitter is approved as a "limited module", then the module manufacturer is responsible for approving the host environment that the limited module is used with. The manufacturer of a limited module must describe, both in the filing and in the installation instructions, the alternative means that the limited module manufacturer uses to verify that the host meets the necessary requirements to satisfy the module limiting conditions.

A limited module manufacturer has the flexibility to define its alternative method to address the conditions that limit the initial approval, such as: shielding, minimum signaling amplitude, buffered modulation/data inputs, or power supply regulation. The alternative method could include that the limited module manufacturer reviews detailed test data or host designs prior to giving the host manufacturer approval.

This limited module procedure is also applicable for RF exposure evaluation when it is necessary to demonstrate compliance in a specific host. The module manufacturer must state how control of the product into which the modular transmitter will be installed will be maintained such that full compliance of the product is always ensured. For additional hosts other than the specific host originally granted with a limited module, a Class II permissive change is required on the module grant to register the additional host as a specific host also approved with the module.

Explanation: The module is not a limited module.

2.5 Trace antenna designs

For a modular transmitter with trace antenna designs, see the guidance in Question 11 of KDB Publication 996369 D02 FAQ – Modules for Micro-Strip Antennas and traces. The integration information shall include for the TCB review the integration instructions for the following aspects: layout of trace design, parts list (BOM), antenna, connectors, and isolation requirements.

- a) Information that includes permitted variances (e.g., trace boundary limits, thickness, length, width, shape(s), dielectric constant, and impedance as applicable for each type of antenna);
- b) Each design shall be considered a different type (e.g., antenna length in multiple(s) of frequency, the wavelength, and antenna shape (traces in phase) can affect antenna gain and must be considered);
- c) The parameters shall be provided in a manner permitting host manufacturers to design the printed circuit (PC) board layout;
- d) Appropriate parts by manufacturer and specifications;
- e) Test procedures for design verification;
- f) Production test procedures for ensuring compliance.

The module grantee shall provide a notice that any deviation(s) from the defined parameters of the antenna trace, as described by the instructions, require that the host product manufacturer must notify the module grantee that they wish to change the antenna trace design. In this case, a Class II permissive change application is required to be filed by the grantee, or the host manufacturer can take responsibility through the change in FCC ID (new application) procedure followed by a Class II permissive change application.

Explanation: No, This module uses a Glue stick antenna.

2.6 RF exposure considerations

It is essential for module grantees to clearly and explicitly state the RF exposure conditions that permit a host product manufacturer to use the module. Two types of instructions are required for RF exposure information:

- (1) to the host product manufacturer, to define the application conditions (mobile, portable – xx cm from a person's body); and (2) additional text needed for the host product manufacturer to provide to end users in their end-product manuals. If RF exposure statements and use conditions are not provided, then the host product manufacturer is required to take responsibility for the module through a change in FCC ID (new application).

Explanation: This module complies with FCC RF radiation exposure limits set forth for an uncontrolled environment. This device should be installed and operated with a minimum distance of 20 centimeters between the radiator and your body." This module is designed to comply with the FCC statement, FCC ID is: 2BDJ6-ME54BS03

2.7 Antennas

A list of antennas included in the application for certification must be provided in the instructions.

For modular transmitters approved as limited modules, all applicable professional installer instructions must be included as part of the information to the host product manufacturer. The antenna list shall also identify the antenna types (monopole, PIFA, dipole, etc. (note that, for example, an “omnidirectional antenna” is not considered to be a specific “antenna type”).

For situations where the host product manufacturer is responsible for an external connector, for example, with an RF pin and antenna trace design, the integration instructions shall inform the installer that a unique antenna connector must be used on the Part 15 authorized transmitters used in the host product. The module manufacturers shall provide a list of acceptable unique connectors.

Explanation: The EUT has a Glue stick antenna, and This module has a unique antenna connector.

2.8 Label and compliance information

Grantees are responsible for the continued compliance of their modules to the FCC rules. This includes advising host product manufacturers that they need to provide a physical or e-label stating “Contains FCC ID” with their finished product. See Guidelines for Labeling and User Information for RF Devices – KDB Publication 784748.

Explanation: The host system using this module, should have label in a visible area indicated the following texts:
"Contains FCC ID: 2BDJ6-ME54BS03

2.9 Information on test modes and additional testing requirements

Additional guidance for testing host products is given in KDB Publication 996369 D04 Module Integration Guide. Test modes should take into consideration different operational conditions for a stand-alone modular transmitter in a host, as well as for multiple simultaneously transmitting modules or other transmitters in a host product.

The grantee should provide information on how to configure test modes for host product evaluation for different operational conditions for a stand-alone modular transmitter in a host, versus with multiple, simultaneously transmitting modules or other transmitters in a host.

Grantees can increase the utility of their modular transmitters by providing special means, modes, or instructions that simulates or characterizes a connection by enabling a transmitter. This can greatly simplify a host manufacturer's determination that a module as installed in a host complies with FCC requirements.

Explanation: Topband can increase the utility of our modular transmitters by providing instructions that simulates or characterizes a connection by enabling a transmitter.

9 STORAGE CONDITIONS

- Please use this product within 6 months after signing the receipt.
 - This product should be stored without opening the package at an ambient temperature of 5~35°C and a humidity of 20~70%RH.
 - This product should be left for more than 6 months after receipt and should be confirmed before use.
 - The product must be stored in a non-corrosive gas (Cl₂, NH₃, SO₂, NO_x, etc.).
 - To avoid damaging the packaging material, do not apply any excessive mechanical shocks, including but not limited to sharp objects adhering to the packaging material and product dropping.
- This product is suitable for MSL2 (based on JEDEC standard J-STD-020).
 - After opening the package, the product must be stored at ≤30°C/<60%RH. It is recommended to use the product within 3-6 months after opening the package.
 - When the color of the indicator in the package changes, the product should be baked before welding.
- Baking is not required for one year if exposure is limited to <30°C and 60%RH. Refer to MSL2 for exposure criteria for moisture sensitivity level. If exposed to (≥168h@85°C/60%RH) conditions or stored for more than one year, recommended baking conditions.
 1. 120 ±5/-5°C, 8 hours, 1 time
Products must be baked individually on heat-resistant trays because the materials (base tape, reel tape, and cover tape) are not heat-resistant, and the packaging material may be deformed at temperatures of 120 °C;
 2. 90 °C ±8/-0 °C, 24hours, 1times
The base tape can be baked together with the product at this temperature. Please pay attention to the uniformity of heat.

10 HANDLING CONDITIONS

- Be careful in handling or transporting products because excessive stress or mechanical shock may break products.
- Handle with care if products may have cracks or damages on their terminals. If there is any such damage, the characteristics of products may change. Do not touch products with bare hands that may result in poor solder ability and destroy by static electrical charge.

11 QUALITY

Cognizant of our commitment to quality, we operate our own factory equipped with state-of-the-art production facilities and a meticulous quality management system. We hold certifications for ISO9001, ISO14001, ISO27001, OHSAS18001, BSCI.

Every product undergoes stringent testing, including transmit power, sensitivity, power consumption, stability, and aging tests. Our fully automated module production line is now in full operation, boasting a production capacity in the millions, capable of meeting high-volume production demands.

12 COPYRIGHT STATEMENT

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13 RELATED DOCUMENTS

- [MinewSemi_Product_Naming_Reference_Manual](https://en.minewsemi.com/file/MinewSemi_Product_Naming_Reference_Manual_EN.pdf)
https://en.minewsemi.com/file/MinewSemi_Product_Naming_Reference_Manual_EN.pdf
- [MinewSemi_Connectivity_Module_Catalogue](https://en.minewsemi.com/file/MinewSemi_Connectivity_Module_Catalogue_EN.pdf)
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